



Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. 17µm [1/2 oz.] Cu clad. SnPb plating.

Pins: material- Brass Alloy 360 1/2 hard; finish-0.25 μ m [10 μ "] Au over 1.27 μ m [50 μ "] Ni (min.).

Stand-off: material- Teflon; 2.29mm[0.090"] dia., 1.52mm[0.060"] thick.

Description: Package Converter

100 position QL3012-100 to 84 position pin array, compatible with AMP 822473 footprint. Pin connection is custom specific.

DC-QFP/PGA-QL3012-S-P-01 Drawing	Status: Released	Scale:	2:1	Rev: A
© 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: E Smolentseva		Date: 09/26/06	
	File: DC-QFP-PGA-QL3012-S-P-01 Dwg		Modified:	

 $\frac{Tolerances:}{PCB \ perimeters \ \pm 0.25mm \ [\pm 0.001"],}$ PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.